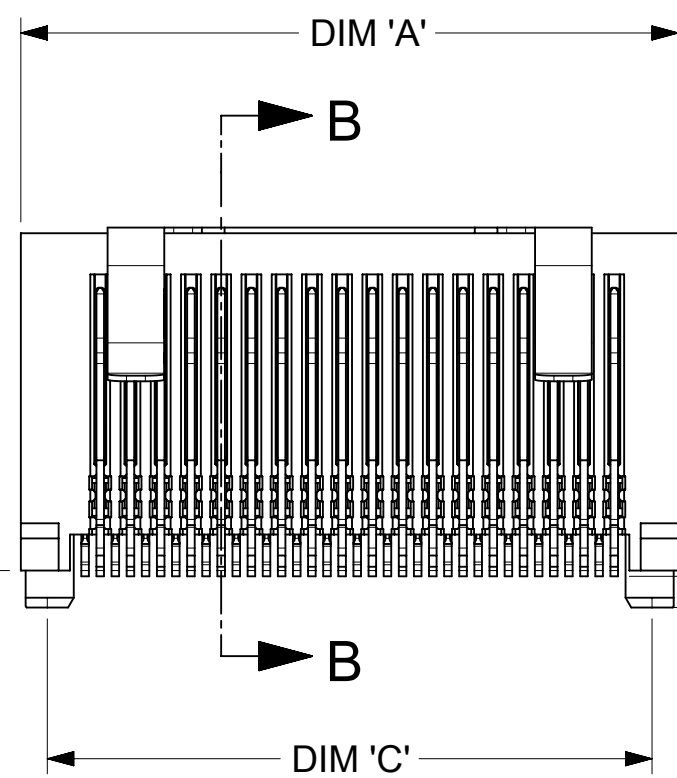
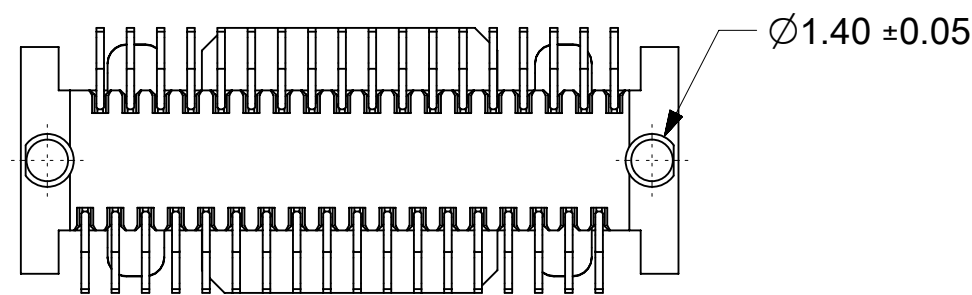


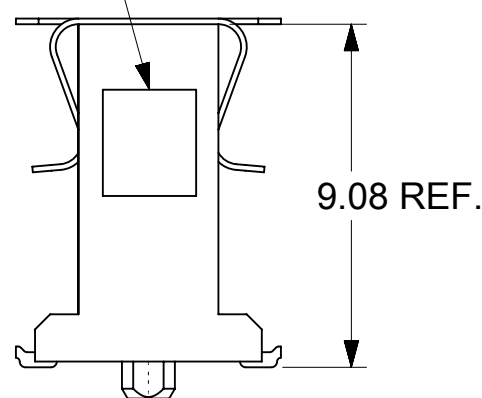
36 CIRCUIT ASSEMBLY SHOWN



SEE NOTE 3

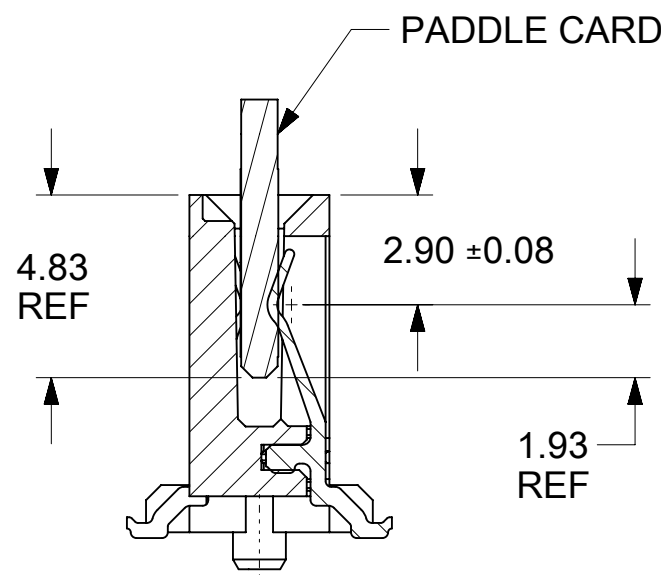


DATE CODE LOCATION  
SEE NOTE 4

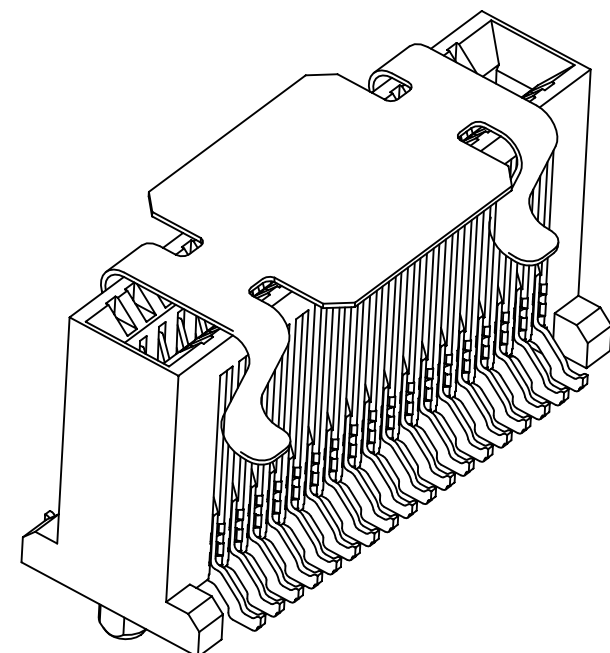


NOTES:

1. MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK  
TERMINALS - COPPER ALLOY
2. TERMINAL PLATING:  
OPTION 1  
CONTACT AREA: 0.38 $\mu$ m HARD GOLD OVER 2.54 $\mu$ m NICKEL  
SOLDER AREA: 2.54-5.09 $\mu$ m TIN OVER 1.27 $\mu$ m NICKEL  
OPTION 2  
CONTACT AREA: 0.76 $\mu$ m HARD GOLD OVER 2.54 $\mu$ m NICKEL  
SOLDER AREA: 2.54-5.09 $\mu$ m TIN OVER 1.27 $\mu$ m NICKEL
3. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/.004 MEASURED FROM FRONT HOUSING STANDOFF (DATUM E)
4. DATE CODE: 4 DIGIT (3 DIGIT DAY, 1 DIGIT YEAR)
5. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
6. MATES WITH:  
A. INTERNAL CABLE SERIES:  
79575/74563/79576/74573/79536/74562/74569/74586  
B. PADDLE CARD PCB: DO NOT BOTTOM OUT PCB IN THE CONNECTOR. SEE SECTION Z-Z.  
USE WITH APPROPRIATE INTERNAL SHELL FROM SD-76010-002
7. LITTLE ROCK PACKAGING PER PK-75577-001  
CHENGDU PACKAGING PER PK-75577-002
8. CONFORMS TO PRODUCT SPECIFICATION PS-75783-001
9. CONFORMS TO APPLICATION SPECIFICATION AS-75783-001



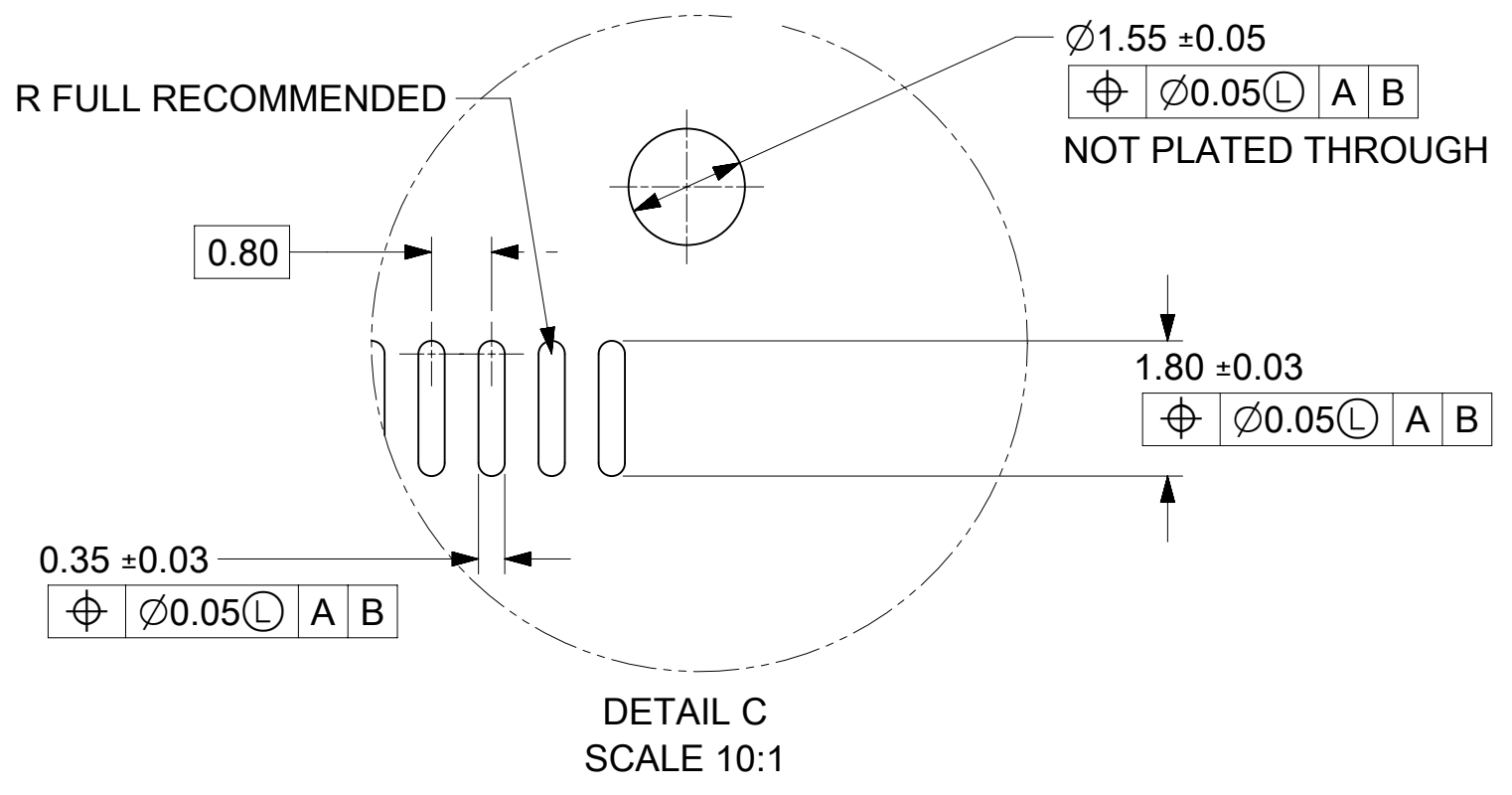
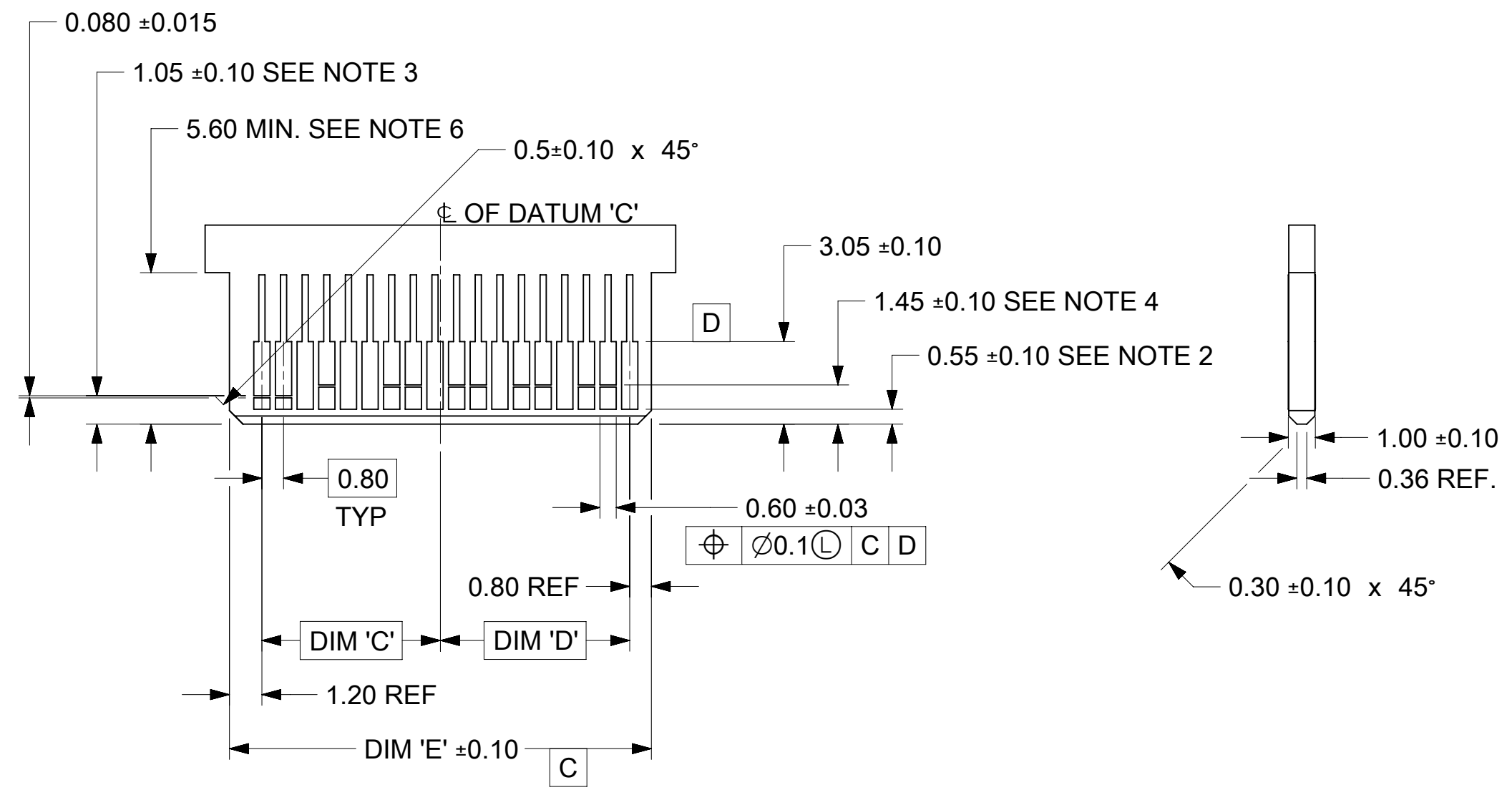
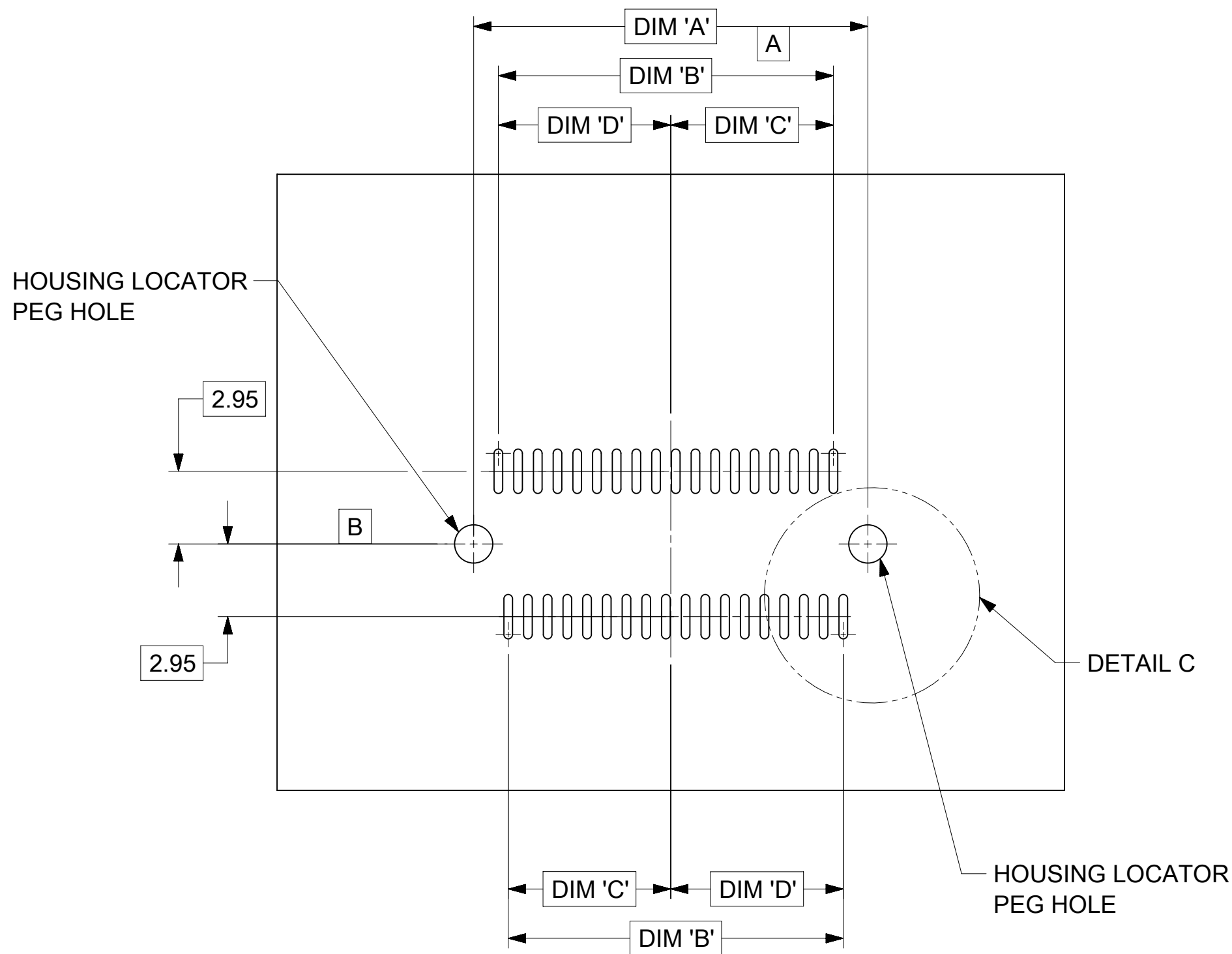
SECTION B-B



CIRCUIT SIZE	MAT'L NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
36	75577-1002	OPTION 1	17.40	15.80	16.00
68	75577-1004	OPTION 1	30.20	28.60	28.80

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS <b>mm</b>	SCALE <b>5:1</b>	CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#511698.		<b>molex</b>		
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 742551				
4 PLACES	±	MM	INCH	DRWN: SANTHN	2023/03/30	PRODUCT CUSTOMER DRAWING
3 PLACES	±			CHK'D: GGA	2023/05/12	
2 PLACES	± 0.13			APPR: GGA	2023/05/12	DOCUMENT NUMBER <b>SD-75577-002</b>
1 PLACE	± 0.25			INITIAL REVISION:		
0 PLACES	±			DRWN: JLSWENSON	06/07/07	DOC PART 001
ANGULAR TOL	± 0.5 °			APPR: MBANAKIS	06/07/07	REVISION <b>E1</b>
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER	CUSTOMER
			<b>C-SIZE</b>	<b>75577</b>	SEE TABLE	GENERAL MARKET
						SHEET NUMBER 1 OF 2



36 CIRCUIT SHOWN  
PATTERN FOR REPRESENTATION ONLY

- NOTES:
1. FOR APPROPRIATE SHELL FOOT PRINT AND KEEP OUT AREAS, SEE SD-76010-002
  2. PAD CONFIGURATION FOR FIRST MATE
  3. PAD CONFIGURATION FOR SECOND MATE
  4. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS)
  5. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION
  6. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE
  7. THESE ARE GENERIC DETAILS THAT DESCRIBES THE CONFIGURATION OF VARIOUS PCB DESIGN ELEMENTS. THE CUSTOMER MUST DETERMINE WHERE AND WHEN TO USE EACH ELEMENT TO ACCOMODATE THEIR SPECIFIC APPLICATION.
  8. CHAMFER ROUGHNESS NOT TO EXCEED 3.17µM.
  9. EDGE CARD CHAMFER NOT TO GO THROUGH GOLD PAD.

	PEG TO PEG	FIRST TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH
CIRCUIT SIZE	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'
26	12.00	9.60	4.60	5.00	11.60
36	16.00	13.60	6.60	7.00	15.60
50	21.60	19.20	9.40	9.80	21.20
68	28.80	26.40	13.00	13.40	28.40

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DIMENSION UNITS	SCALE	CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#511698.	
mm	5:1		
GENERAL TOLERANCES (UNLESS SPECIFIED)			
	MM	INCH	
4 PLACES	±	±	
3 PLACES	±	±	
2 PLACES	± 0.13	±	
1 PLACE	± 0.25	±	
0 PLACES	±	±	
ANGULAR TOL	± 0.5°		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING SERIES
			C-SIZE 75577
DOCUMENT STATUS		DOC TYPE	DOC PART
P1	RELEASE DATE 2023/05/12 06:17:40	PSD	001
		DOC PART	REVISION
		SD-75577-002	E1
MATERIAL NUMBER		CUSTOMER	SHEET NUMBER
SEE TABLE		GENERAL MARKET	2 OF 2